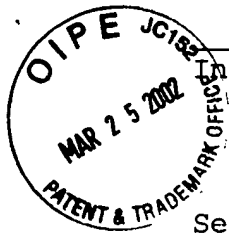


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TONGBI JIANG
EDWARD SCHROCK

Serial No.: 09/258,961

ART UNIT: 2811

Filing Date: March 1, 1999

Examiner: PAREKH, N.

Title: BGA PACKAGE HAVING SUBSTRATE
WITH PATTERNED SOLDER MASK
DEFINING OPEN DIE ATTACH AREA
(AS AMENDED)

Attorney Docket No.: 98-0645.1

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**AMENDMENT SUBMITTED WITH REQUEST FOR CONTINUED
EXAMINATION (RCE) UNDER 37 CFR §1.114**

March 13, 2002

Assistant Commissioner for Patents
BOX RCE
Washington, D.C. 20231

Sir:

This Amendment is being filed with a "Request For Continued Examination (RCE)", and a "Petition For Extension Of Time".

This Amendment is in response to the final Office Action dated October 18, 2001 having a statutory period for response set to expire on January 18, 2002, but extended for 60 days until March 18, 2002 by the enclosed Petition for Extension of Time. Please amend the captioned case as follows.

In the Claims:

Please amend claims 26, 27, 30, 32, 33 and 36. A clean version of the amended claims, and a clean version of all the pending claims follows. In addition, a marked version of the amended claims showing the changes follows the Remarks section.